| | CONNECTING CS INDUSTRIES® MALE TALE MALE TALE MALE TALE MALE TALE MALE TALE MALE TALE MALE TALE MALE TALE MALE TALE COMP | PC, Bannockb | ourn, Illinois. A | All rights reserved untions. | under both | This docume level parts, t | ent is a declaration | tion of the encompas | substances ses all lowe | within the mer level mater | nanufacture ials for wh | er listed ite nich the ma | em. Note: if anufacturer | f the item is an as has engineering | sembly with lowe responsibility. | |
|------------------|---|---------------------------|-------------------------------|------------------------------|-------------------------|-------------------------------|---|-------------------------|----------------------------|---------------------------------|---------------------------------|------------------------------|-----------------------------|--|-------------------------------------|--|
| 1752-21.1 | | | | | Form Type Distribute | | | | | | us Materia | ials and Mfg Information | | | | |
| Supplie | r Information | | | | | | | | | | | | | | | |
| Company name* Co | | | | Company unique ID | | | Unique ID Authority | | | | | Response Date* | | | | |
| onsemi | | | | | | | | | | | | 2023-06-08 | | | | |
| Contact N | lame | Title - Contact | | | | Phone - Contact* | | | | | Email - Contact* | | | | | |
| Product-l | Env-Stewards | Product Enviro Compliance | | | | NA | | | | | Product-Env-Stewards@onsemi.com | | | | | |
| uthorize | ed Representative* | Title - Representative | | | | Phone - Representative* | | | | Email - Representative* | | | | | | |
| Product-l | Env-Stewards | Product Enviro Compliance | | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | | | |
| | Requester Item Number Mfr Item H11AA11 | | | | | | Effective Date Version Manufacturing Sit 2023-06-08 THH | | ng Site | W | /eight* | UOM | Unit Type | | | |
| | | | | | | | | | | 449.722 | | mg | Each | | | |
| /anufa | cturing Proccess Informa | tion | | | | | | | | | | | | | | |
| | Terminal Plating / Grid Array Material | | Ferminal Base Alloy J-STD-020 | | J-STD-020 MSI | L Rating | Peak Process Body Ten | | Temperatu | berature Max Time at Peak | | Temperatu | re Numb | er of Reflow Cyc | les | |
| | Matte Tin (Sn) - annealed | | CU Alloy NA | | | 0 C | | 30 | | second | s 3 | | | | | |
| omments | 5 | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | | |
| or more | information regarding material | composition | please refer to | page 3 | | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | | | | | |
|--|--|--|---|---|---|--|--|--|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | | nium (Cr6+), Polybro | ominated Biphenyls (PBB), Polybron | | y mass (1000 PPM) in homogeneous material for: Lead nd Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl | | | | | | | | | |
| cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the | henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies | RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform | ce of its products with European Union membe | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | | | | | | |
| RoHS Declaration * 1 - Item(s) | does not contain RoHS restricted substa | on above | Supplier Acceptance | * Accepted | | | | | | | | | | |
| Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions. | | | | | | | | | | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | | | | | |
| Declaration Signature | | | | | | | | | | | | | | |
| Instructions: Complete all of the required fin Requester) and click on Submit Form to have | elds on all pages of this form. Select the form returned to the Requester | he "Accepted" on th | e Supplier Acceptance drop-down | . This will display the signature area. Digital | lly sign the declaration (if required by the | | | | | | | | | |
| Supplier Digital Signature Ra | stislav Drska | Le | | | | | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|---------|-----------------|----------|---|------------|--------|---------|-----------------|
| Coupling Gel | 0.4 | mg | Supplier | Dimethyl Cyclosiloxanes | 69430-24-6 | | 0.04 | mg |
| | | | Supplier | Trimethoxy(methyl)silane (C4H12O3Si) | 1185-55-3 | | 0.36 | mg |
| Die | 5.13 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 5.13 | mg |
| Die Attach | 0.3 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.225 | mg |
| | | | Supplier | Phenolic Resin-2 | 54208-63-8 | | 0.075 | mg |
| Lead Frame | 108.322 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.68 | mg |
| | | | Supplier | Zinc (Zn) | 7440-66-6 | | 0.13 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 2.48 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 105 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.032 | mg |
| Mold Compound-White | 327.22 | mg | Supplier | Titanium Dioxide (TiO2) | 13463-67-7 | | 81.805 | mg |
| | | | В | Brominated Bisphenol A Diglycidyl Ether | 40039-93-8 | | 9.8166 | mg |
| | | | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 | | 44.1747 | mg |
| | | | В | Antimony Trioxide (Sb2O3) | 1309-64-4 | | 9.8166 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 163.61 | mg |
| | | | Supplier | Phenolic Resin (Novolac) | 9003-35-4 | | 17.9971 | mg |
| Plating | 6.7 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 6.7 | mg |
| Wire Bond - Au | 1.65 | mg | Supplier | Gold (Au) | 7440-57-5 | | 1.65 | mg |